

Product / Package Information

Package	SSOP
Body Size	
Lead Count	16
Terminal Finish	100 Sn
MS Number	MS011644B

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	7.31 E-02	87.70	877000	50.97		509743
Thermosets	Epoxy Resin	Proprietary	4.17 E-03	5.00	50000	2.91		29062
Thermosets	Phenol Resin	Proprietary	4.17 E-03	5.00	50000	2.91		29062
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.67 E-03	2.00	20000	1.16		11625
Other inorganic materials	Carbon Black	1333-86-3	2.50 E-04	0.30	3000	0.17		1744
Subtotal			8.33 E-02	100	1000000	58.12		581235

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	4.33 E-02	97.57	975706	30.19		301935
Copper & its alloys	Iron	7439-89-6	1.01 E-03	2.28	22789	0.71		7052
Copper & its alloys	Zinc	7440-66-6	5.60 E-05	0.13	1263	0.04		391
Copper & its alloys	Phosphorus	7723-14-0	1.08 E-05	0.02	242	0.01		75
Subtotal			4.44 E-02	100.00	1000000	30.95		309452

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.16 E-03	100.0	1000000	0.81		8092

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	2.12 E-03	100.0	1000000	1.48		14789

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	3.27 E-04	99.00	990000	0.23		2279
Precious metals	Palladium	7440-05-3	3.30 E-06	1.00	10000	0.002		23
Subtotal			3.30 E-04	100.00	1000000	0.23		2302

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	9.92 E-03	100.0	1000000	6.92		69201

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.71 E-03	80.00	800000	1.19		11943
Thermosets	Epoxy Resin	Proprietary	3.21 E-04	15.00	150000	0.22		2239
Others	Curing agent & hardener	Proprietary	1.07 E-04	5.00	50000	0.07		746
Subtotal			2.14 E-03	100	1000000	1.49		14928

Package Totals	Weight (g)	Percentage (%)	PPM
	1.43 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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